



**PRODUCT SPECIFICATION**

**CKM PN: 3001 SERIES**

**3001 SERIES CONNECTOR  
(HIGH CONDUCTIVITY)**

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**REVISION HISTORY:**

REV	REVISION DESCRIPTION	DATE	CREATED/REVISED
A	NEW RELEASE	2022/05/31	Rock
B	UPDATE AWG	2023/08/14	Rock

<b>REVISION:</b> <b>B</b>	<b>ECR/ECN INFORMATION:</b> EC No.: EC-23080157 DATE: 2023/08/14	<b>TITLE:</b> WIRE TO BOARD 3001 SERIES	<b>SHEET No.</b> 1 of 8
<b>DOCUMENT NUMBER:</b> <b>PS-3001-002</b>		<b>CREATED/REVISED</b>	<b>CHECKED BY</b>
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**1.0 SCOPE**

This specification defines the detailed requirements for the WIRE TO BOARD 3001 SERIES.

**2.0 REQUIREMENTS**

2.1 Materials

2.1.1 Insulator

High temperature thermoplastic, UL94V-0 rated.  
Color-Option.

2.1.2 Pin Contacts

High conductivity copper alloy.  
Matte tin or gold plating, under nickel plating over all.

2.2 Ratings:

2.2.1 Voltage Rating: 250 Vrms maximum.

2.2.2 Current and Applicable Wires

AWG	Max. Outside Insulation Diameter
16	2.00 mm
18	1.85 mm
20	1.85 mm
22	1.85 mm
24	1.85 mm
26	1.27 mm
28	1.27 mm
30	1.27 mm

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## CURRENT DERATING REFERENCE INFORMATION

AWG	2 PIN	3~4 PIN	5~8 PIN	9~10 PIN	11~12 PIN	13~18 PIN t	19~24 PIN
16	12.5A	11.6A	10.1A	9.5A	9A	8.1A	8A
18	10.3A	9.3A	7.7A	7A	6.5A	5.5A	5.5A
20	8.5A	7.3A	5.3A	4.6A	4A	3.7A	3.7A
22	6A	4.5A	4.5A	4A	4A	3.2A	3.2A
24	5.5A	4.5A	4.5A	3.5A	3.5A	3A	3A
26	4.5A	4A	3.8A	3.4A	3A	2.3A	2.2A
28	4A	3A	3A	3A	3A	2A	2A
30	3.5A	3A	3A	2.5A	2.5A	1.5A	1A

\*\*Testing conducted with tinned copper conductor stranded wire. Above charts are intended as a guideline. Current rating is application dependent. Appropriate de-rating is required depending on factors such as higher ambient temperature, smaller copper weight of PCB traces, gross heating from adjacent modules or components and other factors that influence connector performance.

- 1) Values are for REFERENCE ONLY.
- 2) Current de-ratings are based on not exceeding 30°C temperature rise.
- 3) PCB trace design can greatly affect temperature rise results in Wire-to Board applications.
- 4) Data is for all circuits powered.

2.3 Operating Temperature: -40°C to +105°C

### 3.0 PACKAGING AND SHIPPING

Per CKM packing specification.

### 4.0 PERFORMANCE REQUIREMENTS AND TEST DESCRIPTIONS

The product is designed to meet the electrical, mechanical and environmental performance requirements specified in paragraph 5.0 . Unless otherwise specified, all tests are performed at ambient environmental conditions.

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## 5.0 TEST REQUIREMENTS AND PROCEDURES SUMMARY

TEST ITEM		REQUIREMENT	PROCEDURE
1	Examination of Product	Meets requirements of product drawing. No physical damage.	Visual inspection
<b>ELECTRICAL REQUIREMENT</b>			
2	Low Level Contact Resistance	Initial - 10 milliohms maximum per mated pair Final - $\Delta R = 20$ milliohms maximum per mated pair	Per EIA-364-23 Subject mated contacts assembled in housing to closed circuit current of 100mA maximum at open circuit at 20 mV maximum.
3	Contact Resistance on Crimped Portion	5 milliohms MAXIMUM	Terminate the applicable wire to the terminal and measure wire using a voltage of 20 mV and a current of 100mA.
4	Insulation Resistance	1,000Megohms minimum	Per EIA-364-21 Unmate & unmount connectors: apply a voltage of 500 VDC between adjacent terminals and between terminals to ground.
5	Dielectric withstanding Voltage	no breakdown Current leakage < 5mA	Per EIA-364-20 Unmate connectors: apply a voltage of two times the rated voltage plus 1000 volts VAC for 1 minute between adjacent terminals and between terminals to ground.
6	Temperature Rise (Via Current Cycling)	Temperature rise: +30°C MAXIMUM	Mate connector: measure the temperature rise at the rate current after: 1) 96 hours (steady state) 2) 240 hours (45 minutes ON and 15 minutes OFF per hour) 3) 96 hours (steady state)

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## MECHANICAL REQUIREMENT

7	Insertion Force and Withdrawal Force	Insertion Force : 8.0 N maximum /per pin Withdrawal Force: 2.0 N minimum /per pin	Per EIA-364-13 Subject connector to mate and unmate to measure the mechanical forces required to engage and disengage at a rate of 25+/-6 mm per minute Record by using autograph.
8	Crimp Terminal Retention Force (in Housing)	24.5 N minimum.	Axial pullout force on the terminal in the housing at a rate of 25 ± 6 mm per minute.
9	Crimp Terminal Insertion Force (into Housing)	14.7 N maximum.	Apply an axial insertion force on the terminal at a rate of 25+/-6 mm per minute.
10	Pin Retention Force (in Header)	13.7 N minimum pushout force.	Apply an axial extraction force to pin at a rate of 25+/-6mm per minute.
11	Wire Pullout Force (Axial) (Wire from Terminal)	minimum pullout force AWG#16 ~ 20 57.8 N AWG#22 35.6 N AWG#24 22.2 N AWG#26 13.3 N AWG#28 8.9 N AWG#30 6.6 N	Apply an axial pullout force on the wire at a rate of 25+/-6mm per minute.
12	Thumb Latch to Ramp Yield Strength	68.4 N minimum Yield Strength.	Full mate and then unmated the connector at a rate of 25+/-6mm per minute.
13	Durability	No evidence of damage The contact resistance: $\Delta R=20$ milliohms maximum (Final)	Per EIA-364-09 30 mating/ unmating cycles at a maximum rate of 10 cycles per minute.

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14	Vibration (Random)	1) No discontinuities of 1 $\mu$ s or longer duration. 2) Contact resistance: $\Delta R=20$ milliohms maximum 3) No physical damage.	Mate connectors and vibrate per EIA 364-28, test condition VII, Letter D. Test Duration: 15minutes each axis.
15	Shock (Mechanical)	1) No discontinuities of 1 $\mu$ s or longer duration. 2) Contact resistance: $\Delta R=20$ milliohms maximum 3) No physical damage.	Mate connectors and shock at 50 g's with $\frac{1}{2}$ sine wave (11 milliseconds) shocks in the $\pm X, \pm Y, \pm Z$ axes (18 shocks total). (Per EIA-364-27, Test Condition H)

## ENVIRONMENTAL REQUIREMENTS

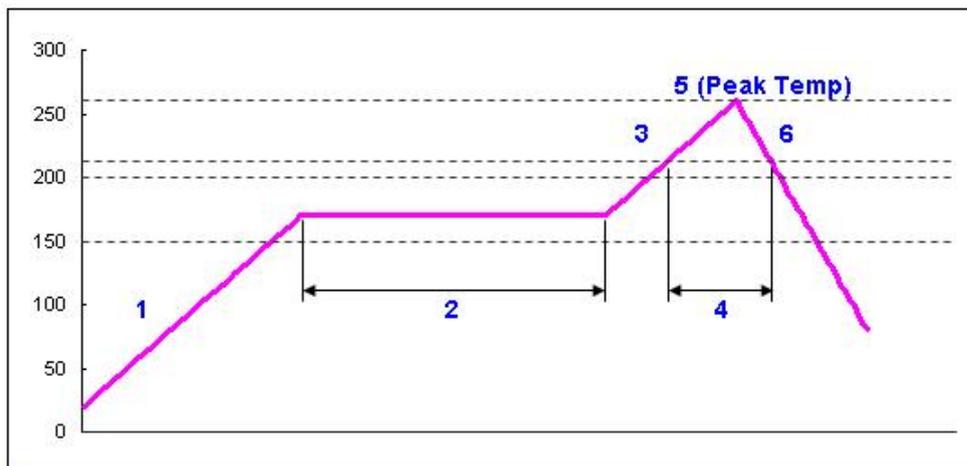
16	Solderability	Continuous solder coating with a minimum 95% coverage.	Per EIA-364-52 Steam age 1hr. Solder time $5 \pm 0.5$ seconds. Solder Temperature: $245 \pm 5^\circ\text{C}$ Nonactivated flux.
17	Salt Spray	No evidence of damage. Contact resistance: $\Delta R=20$ milliohms maximum (Final)	Per EIA-364-26 test condition A Subject mated and unmated connectors should be tested according to the condition listed below: Temperature: $35 \pm 1.1^\circ\text{C}$ Humidity: 95~98% (R.H.) PH value: 6.5~7.2 Duration: 48 hours
18	Resistance to Soldering Heat	No evidence of damage. Verify components meet their specified electrical performance criteria and no physical damage has occurred.	Per EIA-364-56 Dip connector terminal tails in solder: Solder Duration: $10 \pm 0.5$ seconds; Solder temperature: $260 \pm 5^\circ\text{C}$  (refer to FIGURE 1 IR reflow profile) IR reflow test condition: Peak temperature: $260+0 / -10^\circ\text{C}$ Preheating temperature: $150 - 200^\circ\text{C}$ , 60 to 120 sec.  Apply solder iron in solder tail Temperature: $350 \pm 10^\circ\text{C}$ , 3~4 sec.
19	Thermal Aging	No evidence of damage. Contact resistance: $\Delta R=20$ milliohms maximum (Final)	Mate connectors: expose to: 240 hours at $105 \pm 2^\circ\text{C}$

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20	Humidity (Steady State)	1) $\Delta R=20$ milliohms maximum (Final) 2) Dielectric Withstanding Voltage: No Breakdown at 500 VAC 3) Insulation Resistance: 1000 Megohms Minimum.	Mate connectors: expose to a temperature of $40 \pm 2^\circ\text{C}$ with a relative humidity of 90-95% for 96 hours. Note: Remove surface moisture and air dry for 1 hour prior to measurements.
21	Cold Resistance	$\Delta R=20$ milliohms maximum (Final)	Mate connectors: Duration: 96 hours, Temperature: $-40 \pm 3^\circ\text{C}$

NOTE: Shall meet visual requirements, show no physical damage, and meet requirement of additional tests as specified in the test sequence in paragraph 6.0.



1	Average ramp rate	3°C per second max.
2	Pre-heat temp.(minimum)	150°C
	Pre-heat temp.(maximum)	200°C
	Pre-heat time	60 to 120 seconds
3	Ramp to peak	3°C per second max.
4	Time over liquidus(217°C )	60 to 150 seconds
5	Peak temp.	260 +0/-10°C
	Time within 5°C of peak	10 seconds max.
6	Ramp- cool down	6°C per second max.
	Time 25°C to peak	8 minutes max.

FIGURE 1

### RESISTANCE TO REFLOW SOLDERING HEAT

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## 6.0 RODUCT QUALIFICATION AND REQUALIFICATION TEST SEQUENCE

	A	B	C	D	E	F	G	H	I	J	K
Examination of Product	1,7	1,11	1,7	1,5	1,3	1	1	1	1	1	1,5
Low Level Contact Resistance	2,6	2,6, 10	2,4,6	2,4							2,4
Contact Resistance on Crimped Portion									2		
Insulation Resistance		3,8									
Dielectric Withstanding Voltage		4,9									
Temperature Rise				3							
Insertion Force and Withdrawal Force	3,5										
Crimp Terminal Retention Force (in Housing)								3			
Crimp Terminal Insertion Force (into Housing)								2			
Pin Retention Force (in Header)							3				
Wire Pullout Force (Axial) (Wire from Terminal)									3		
Thumb Latch to Ramp Yield Strength										2	
Durability	4										
Vibration (Random)			3								
Shock (Mechanical)			5								
Solderability					2						
Salt Spray						2					
Resistance to Soldering Heat							2				
Thermal Aging		5									
Humidity (Steady State)		7									
Cold Resistance											3
Sample Size per Test Group	5	5	5	5	5	5	5	5	5	5	5

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